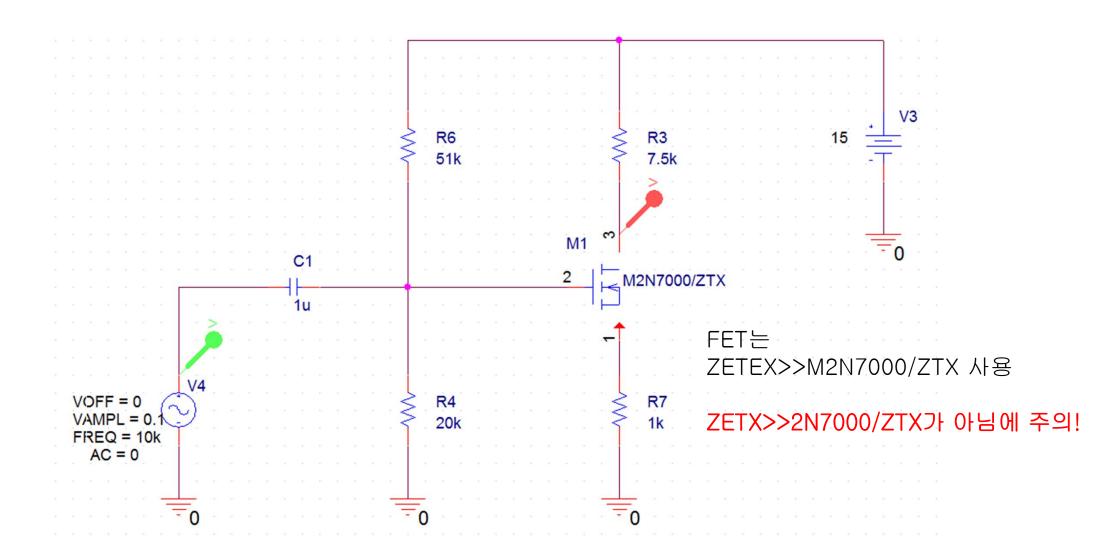
FET 증폭기









2N7000 2N7002

N-channel 60 V, 1.8 Ω, 0.35 A, SOT23-3L, TO-92 STripFET™ Power MOSFET

Features

Туре	V _{DSS}	R _{DS(on)} max	ID
2N7000	60 V	< 5Ω(@10V)	0.35 A
2N7002	60 V	< 5Ω(@10V)	0.20 A

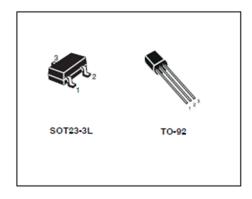
- Low Q_a
- Low threshold drive

Application

Switching applications

Description

This Power MOSFET is the second generation of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.



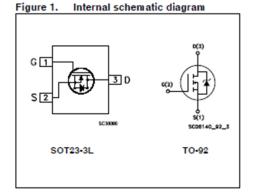


Table 1. Device summary

Order codes Marking		Package	Packaging
2N7000	2N7000G	TO-92	Bulk
2N7002	ST2N	SOT23-3L	Tape and reel



Table 2. Absolute maximum ratings

•	Symbol	Parameter	Val	Unit	
			TO-92	SOT23-3L	Jiii
\	V_{DS}	Drain-source voltage (V _{GS} = 0)	60 60		V
	V _{DGR}	Drain-gate voltage (R_{GS} = 20 kΩ)			V
	V_{GS}	te- source voltage ± 18		18	V
→	I _D	Drain current (continuous) at T _C = 25 °C	0.35	0.20	Α
	I _{DM} ⁽¹⁾	Drain current (pulsed)	1.4	1	Α
	P _{TOT}	Total dissipation at T _C = 25 °C	1	0.35	W

^{1.} Pulse width limited by safe operating area



Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0$	60			٧
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	V_{DS} = max rating V_{DS} = max rating, T_{C} = 125 °C			1 10	μ Α μ Α
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	V _{GS} = ± 18 V			±100	nA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2.1	3	٧
R _{DS(on)}	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$		1.8 2	5 5.3	Ω



Table 5. Dynamic

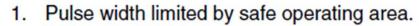
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 0.5 \text{ A}$		0.6		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V, f} = 1 \text{ MHz,}$ $V_{GS} = 0$		43 20 6		pF pF pF
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 30 \text{ V}, I_{D} = 0.5 \text{ A}$ $R_{G} = 4.7 \Omega V_{GS} = 4.5 \text{ V}$ (see <i>Figure 16</i>)		5 15 7 8		ns ns ns
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 30 \text{ V}, I_D = 1 \text{ A},$ $V_{GS} = 5 \text{ V}$ (see Figure 17)		1.4 0.8 0.5	2	nC nC nC

1. Pulsed: Pulse duration = 300 μs, duty cycle 1.5%.



Table 6. Source drain diode

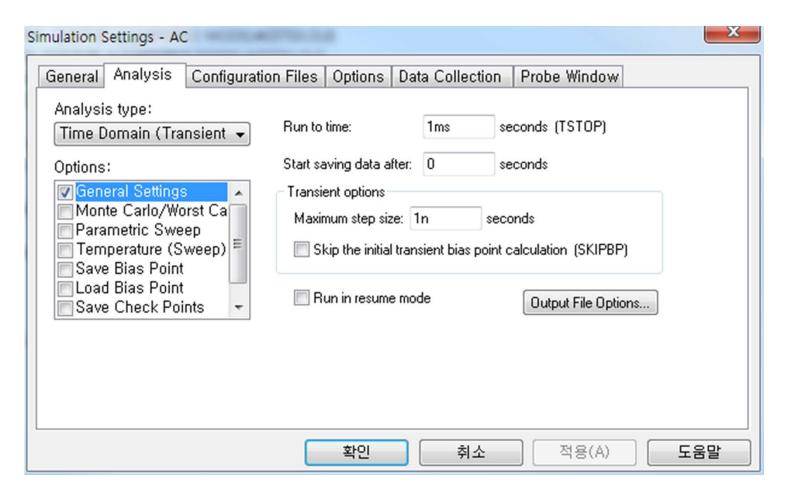
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current Source-drain current (pulsed)				0.35 1.40	A A
V _{SD} (2)	Forward on voltage	I _{SD} = 1 A, V _{GS} = 0			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 1 \text{ A, di/dt} = 100 \text{ A/µs,}$ $V_{DD} = 20 \text{ V, T}_{j} = 150 ^{\circ}\text{C}$ (see <i>Figure 18</i>)		32 25 1.6		ns nC A



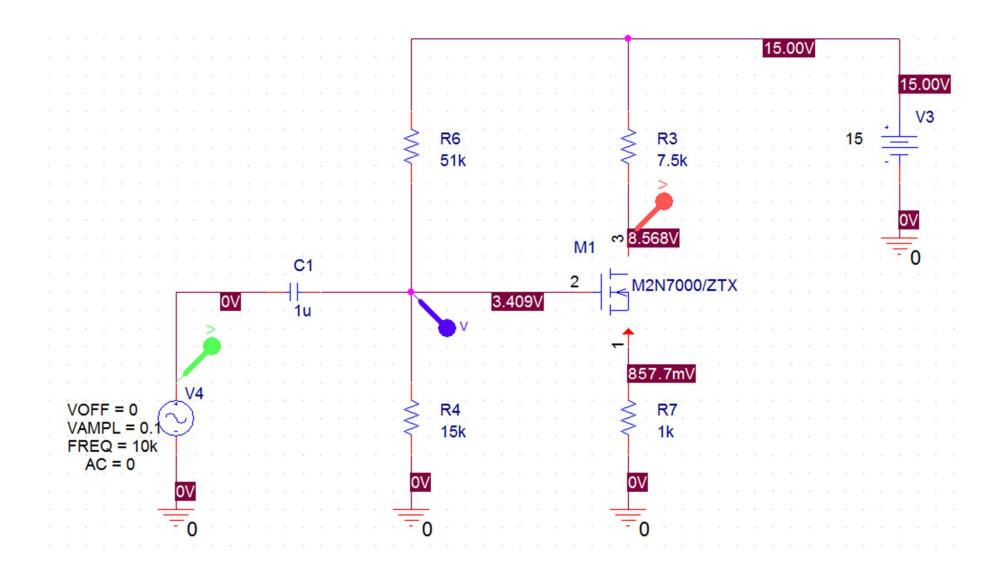
2. Pulsed: Pulse duration = 300 μs, duty cycle 1.5%



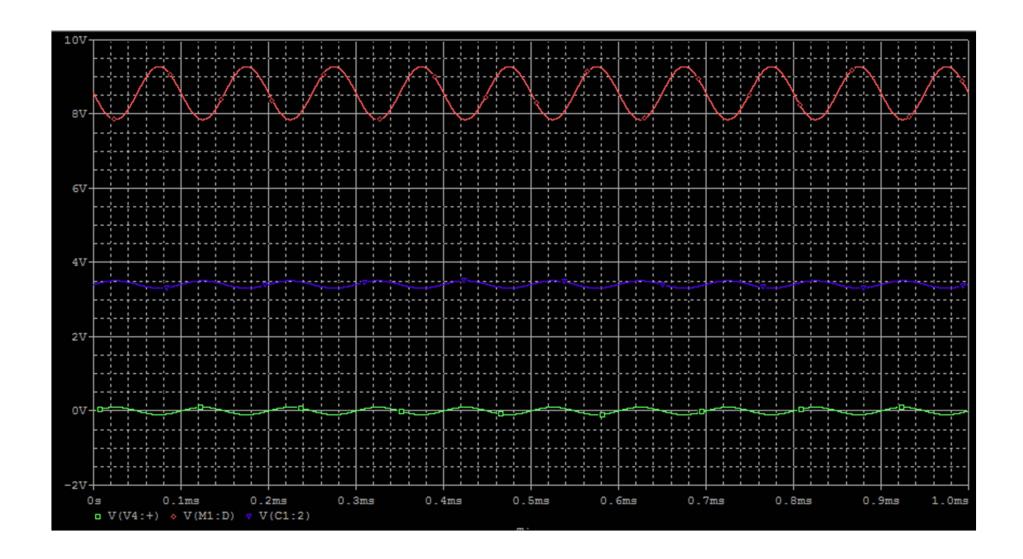
Transient Analysis 0~1ms까지, 1ns 정밀도



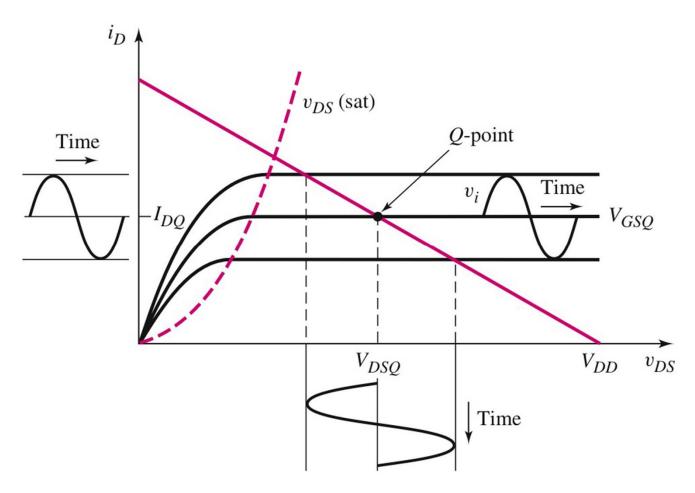






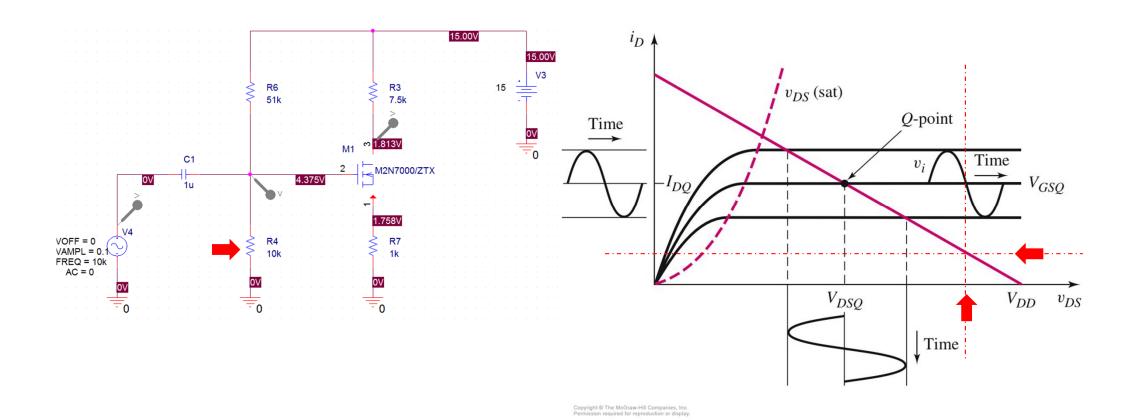




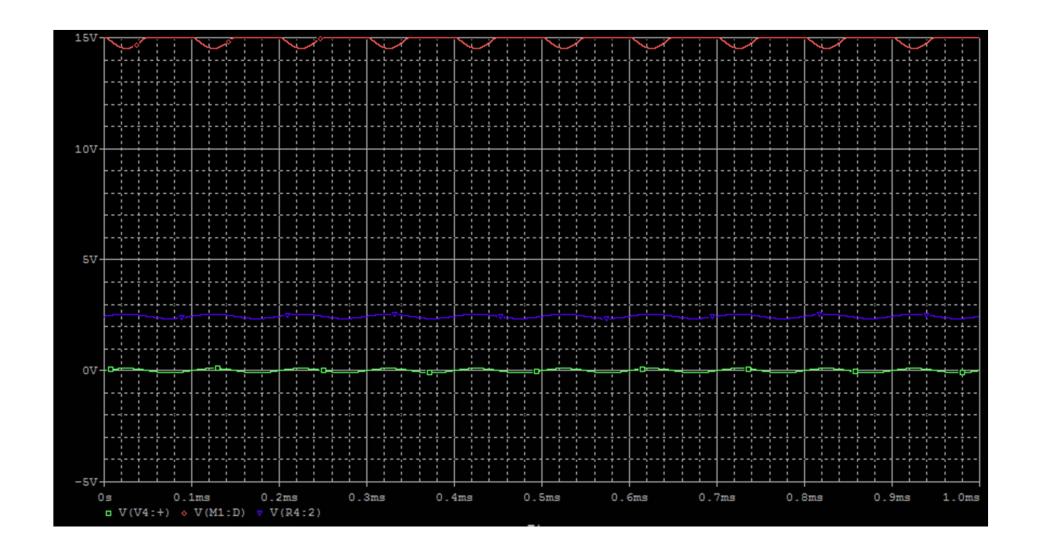


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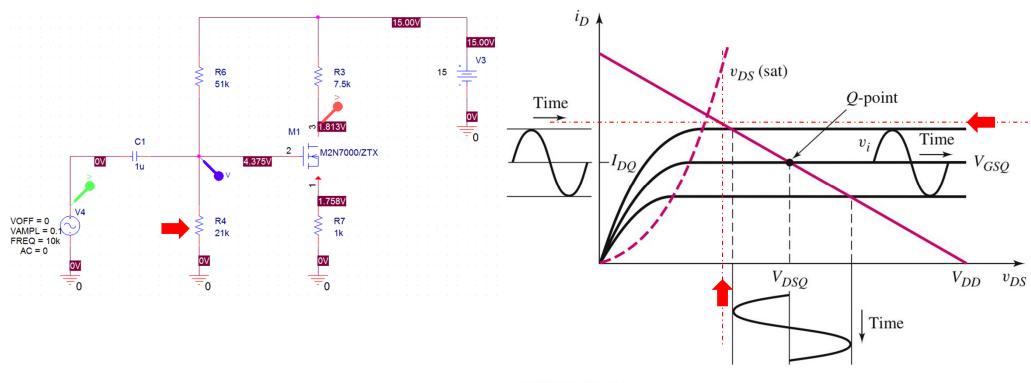












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